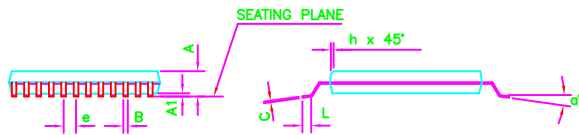
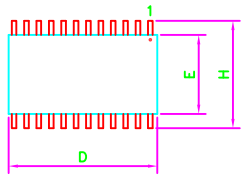


150 MIL QSOP  
 QUARTER SIZE OUTLINE PACKAGE(QSOP)

PACKAGE INFORMATION (AS16xx)

NOTES

1. LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
3. ALLOWABLE MOLD FLASH IS 5 MILS PER SIDE.
4. DIMENSIONS ARE GIVEN IN INCHES.
5. LEAD COPLANARITY IS 0.003 INCH MAX.



JEDEC #	MO-137AB	
TYPE	16 LEAD	
SYMBOL	Min	Max
A	0.060	0.068
A1	0.004	0.008
B	0.009	0.012
C	0.007	0.010
D	0.188	0.197
E	0.150	0.157
e	0.025 BSC	
H	0.230	0.244
h	0.010	0.016
L	0.023	0.029
L'	0"	8"

PREPARED BY: XX  
 CHECKED BY: XX  
 APPROVED BY: XXX

REF. NO.  
 DIM-QSOP-01

REV. NO.  
 2  
 DATE  
 11.02.01

AKROS SILICON  
 USA

